



Material Content Data Sheet



Sales Product Name	TLE8880TN2			Issued	31. July 2018			
MA#	MA001797282							
Package	PG-TO220-5-12			Weight*	2128.95 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.531	0.64	0.64	6356	6356
leadframe	inorganic material	phosphorus	7723-14-0	0.277	0.01		130	
	non noble metal	iron	7439-89-6	0.923	0.04		433	
	non noble metal	copper	7440-50-8	921.567	43.28	43.33	432875	433438
	non noble metal	aluminium	7429-90-5	3.140	0.15	0.15	1475	1475
wire	non noble metal	aluminium	7429-90-5	3.140	0.15	0.15	1475	1475
encapsulation	organic material	carbon black	1333-86-4	8.440	0.40		3964	
	plastics	epoxy resin	-	92.842	4.36		43609	
	inorganic material	silicondioxide	60676-86-0	461.399	21.67	26.43	216726	264299
leadfinish	non noble metal	tin	7440-31-5	24.181	1.14	1.14	11358	11358
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		4	
	non noble metal	nickel	7440-02-0	3.285	0.15	0.15	1543	1547
solder	non noble metal	tin	7440-31-5	0.182	0.01		86	
	noble metal	silver	7440-22-4	0.228	0.01		107	
	non noble metal	lead	7439-92-1	8.713	0.41	0.43	4093	4286
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		83	
	non noble metal	iron	7439-89-6	0.590	0.03		277	
	non noble metal	copper	7440-50-8	589.466	27.69	27.73	276881	277241
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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